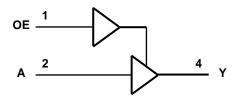


Pin Descriptions

Pin Name	Description
OE	Output Enable (active high)
А	Data Input
GND	Ground
Y	Data Output
Vcc	Supply Voltage

Logic Diagram



Function Table

Inp	Inputs					
OE	OE A					
Н	Н	Н				
Н	L	L				
L	Х	Z				



Absolute Maximum Ratings (Note 3)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V _{cc}	Supply Voltage Range	-0.5 to 6.5	V
Vı	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high impedance or I _{OFF} state	-0.5 to 6.5	V
Vo	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
Io	Continuous output current	±50	mA
	Continuous current through Vdd or GND	±100	mA
T _J	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Note: 3. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



Recommended Operating Conditions (Note 4)

Symbol		Parameter	Min	Max	Unit	
V	On a ratio a Valta sa	Operating	1.4	5.5	V	
V _{cc}	Operating Voltage	Data retention only	1.2		V	
		V _{CC} = 1.4 V to 1.95 V	0.65 X V _{CC}			
V	High Loyal Input Valtage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
V_{IH}	High Level Input Voltage	V _{CC} = 3 V to 3.6 V	2		V	
		V _{CC} = 4.5 V to 5.5 V	0.7 X V _{CC}			
		V _{CC} = 1.4 V to 1.95 V		0.35 X V _{CC}		
\/	Lavelavalland Valtana	V _{CC} = 2.3 V to 2.7 V		0.7	V	
V_{IL}	Low Level Input Voltage	V _{CC} = 3 V to 3.6 V		0.8	V	
		V _{CC} = 4.5 V to 5.5 V		0.3 X V _{CC}		
VI	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	V _{CC}	V	
	, High Level Output	Vcc=1.4 V		-3		
		V _{CC} = 1.65 V		-4	A	
ı		V _{CC} = 2.3 V		-8		
I _{OH}	Current	V 2V		-16	mA	
		$V_{CC} = 3 V$		-24		
		V _{CC} = 4.5 V		-32		
		Vcc=1.4 V		3		
		V _{CC} = 1.65 V		4		
	Low Level Output	V _{CC} = 2.3 V		8	mΑ	
I _{OL}	Current			16	1	
		$V_{CC} = 3 V$		24		
		V _{CC} = 4.5 V		32		
		V _{CC} = 1.4 to 3V		20		
Δt/ΔV	Input transition rise or fall	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V	
	rate	$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5		
T _A	Operating free-air temperature		-40	85	°C	

Note: 4. Unused inputs should be held at Vcc or Ground.



Electrical Characteristics (All typical values are at Vcc = 3.3V, T_A = 25°C)

Over recommended free-air temperature range (unless otherwise noted)

Symbol	Parameter	Test Conditions	Vcc	Min	Тур.	Max	Unit
		I _{OH} = -100μA	1.4 V to 5.5V	V _{CC} - 0.1			
		$I_{OH} = -3mA$	1.4 V	1.05			
		$I_{OH} = -4mA$	1.65 V	1.2			
V_{OH}	High Level Output Voltage	$I_{OH} = -8mA$	2.3V	1.9			V
	Voltage	$I_{OH} = -16mA$	3 V	2.4			
		$I_{OH} = -24mA$	3 V	2.3			
		$I_{OH} = -32mA$	4.5 V	3.8			
		$I_{OL} = 100 \mu A$	1.4 V to 5.5V			0.1	
		$I_{OL} = 3mA$	1.4V			.4	
		$I_{OL} = 4mA$	1.65 V			0.45	
V_{OL}	Low Level Output Voltage	$I_{OL} = 8mA$	2.3V			0.3	V
	Voltage	$I_{OL} = 16mA$	2.1/			0.4	
		$I_{OL} = 24mA$	3 V			0.55	
		$I_{OL} = 32mA$	4.5			0.55	
I _I	Input Current	$V_1 = 5.5 \text{ V or GND}$	0 to 5.5 V			± 5	μΑ
I _{OFF}	Power Down Leakage Current	V_1 or $V_0 = 5.5V$	0			± 10	μA
I _{OZ}	Z State Leakage Current	V _O =0 to 5.5V	3.6V			10	μA
I _{cc}	Supply Current	$V_1 = 5.5V$ of GND $I_0=0$	1.4 V to 5.5V			10	μA
ΔI _{CC}	Additional Supply Current	One input at V _{CC} – 0.6 V Other inputs at V _{CC} or GND	3 V to 5.5V			500	μA
Ci	Input Capacitance	$V_i = V_{CC} - \text{ or GND}$	3.3		3.5		pF
		SOT25	(Note 5)		204		
θ_{JA}	Thermal Resistance Junction-to-Ambient SOT353		(Note 5)		371		°C/W
	Julionolion-to-Ambient	DFN1410	(Note 5)		430		
	T. 15	SOT25	(Note 5)		52		
θ_{JC}	Thermal Resistance Junction-to-Case	SOT353	(Note 5)		143		°C/W
	ouriolion-to-oase	DFN1410	(Note 5)		190		

Note: 5. Test condition for SOT25, SOT353 and DFN1410: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Switching Characteristics

Over recommended free-air temperature range, CL = 15pF (see Figure 1)

Parameter	neter From TO	Vcc = ± 0			: 1.8 V .15V		: 2.5 V).2V		3.3 V 3.3V	Vcc :	= 5 V).5V	Unit	
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	Α	Υ	1.7	6.9	1.1	4.8	0.4	3.6	0.4	3	0.4	3	ns

Over recommended free-air temperature range, CL = 30 or 50pF as noted (see Figure 2)

Parameter	From TO		± 0.1V					Vcc = 2.5 V ± 0.2V		Vcc = 3.3 V ± 0.3V		Vcc = 5 V ± 0.5V	
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
t _{pd}	Α	Y	2.6	8	1.8	5.6	0.8	4.4	0.8	3.6	0.9	3.6	ns
t _{en}	ŌE	Υ	2.8	9.4	1.9	6.5	1	5.2	0.9	4.3	0.9	4.3	
t _{dis}	ŌE	Y	1.6	9.8	1.1	6.8	0.8	4.4	0.8	4.5	0.9	3.7	

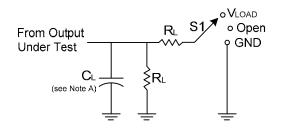
Operating Characteristics

 $T_A = 25$ °C

	Parame	ter	Test Conditions	Vcc = 1.5 V	Vcc = 1.8 V	Vcc = 2.5 V	Vcc = 3.3 V	Vcc = 5 V	Unit
	Power	Outputs enabled	f 10 MU-	19	19	19	19	19	5.F
C _{pd}	dissipation capacitance	Outputs disabled	f = 10 MHz	2	2	2	3	4	pF

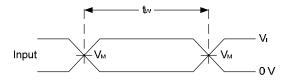


Parameter Measurement Information

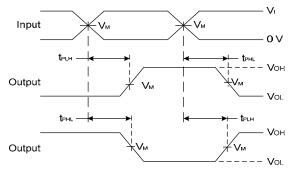


TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	Vload
t _{PHZ} /t _{PZH}	GND

Vcc	In	puts	V	0.	RL
VCC	Vı	t _r /t _f	· V _M	CL	ΚL
1.5V±0.1V	V _{CC}	≤2ns	V _{CC} /2	15pF	1ΜΩ
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	15pF	1ΜΩ
2.5V±0.2V	V _{cc}	≤2ns	V _{CC} /2	15pF	1ΜΩ
3.3V±0.3V	3V	≤2.5ns	1.5V	15pF	1ΜΩ
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	15pF	1ΜΩ



Voltage Waveform Pulse Duration



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Output
Control

Output
Waveform 1
S1 at V_{LOAD}
(see Note B)

Output
Waveform 2
S1 at GND
(see Note B)

Output
Waveform 2
S1 at GND
(see Note B)

Voltage Waveform Enable and Disable Times
Low and High Level Enabling

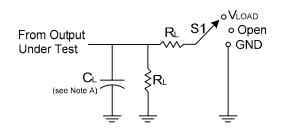
Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
- C. Inputs are measured separately one transition per measurement.
- D. t_{PLZ} and t_{PHZ} are the same as $t_{dis.}$
- E. t_{PZL} and t_{PZH} are the same as t_{EN} .
- F. t_{PLH} and t_{PHL} are the same as t_{PD} .

Figure 1. Load Circuit and Voltage Waveforms

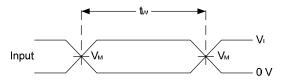


Parameter Measurement Information (Continued)

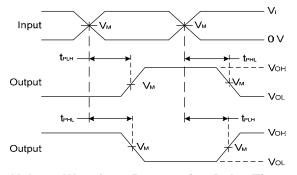


TEST	S1
t _{PLH} /t _{PHL}	Open
t_{PLZ}/t_{PZL}	Vload
t _{PHZ} /t _{PZH}	GND

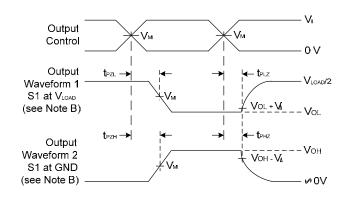
Vcc	Inj	outs	V _M	CL	RL
	Vi	t _r /t _f	- IVI	OL.	
1.5V±0.1V	V _{cc}	≤2ns	V _{CC} /2	30pF	1ΚΩ
1.8V±0.15V	V _{cc}	≤2ns	V _{CC} /2	30pF	1ΚΩ
2.5V±0.2V	V _{cc}	≤2ns	V _{CC} /2	30pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω
5V±0.5V	V _{cc}	≤2.5ns	V _{CC} /2	50pF	500Ω



Voltage Waveform Pulse Duration



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs



Voltage Waveform Enable and Disable Times Low and High Level Enabling

February 2011

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Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
- C. Inputs are measured separately one transition per measurement.
- D. t_{PLZ} and t_{PHZ} are the same as $t_{dis.}$
- E. t_{PZL} and t_{PZH} are the same as t_{EN0}
- F. t_{PLH} and t_{PHL} are the same as $t_{\text{PD.}}$

Figure 2. Load Circuit and Voltage Waveforms



Ordering Information

74LVCE1G 126 XXX - 7

Logic Device

Function

Package

Packing

74 : Logic Prefix

126: 3-State Buffer

W5 : SOT25

7: Tape & Reel

LVCE: 1.4 to 5.5V Family OE-High

SE: SOT353 FZ4: DFN1410

1G: One gate

	Device	Package	Packaging	7" Tape and Reel	
	Device	Code	(Note 5)	Quantity	Part Number Suffix
Pb ,	74LVCE1G126W5-7	W6	SOT25	3000/Tape & Reel	-7
Pb ,	74LVCE1G126SE-7	SE	SOT353	3000/Tape & Reel	-7
Pb	74LVCE1G126FZ4-7	FZ4	DFN1410	5000/Tape & Reel	-7

Note: 6. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



Marking Information

(1) SOT25 and SOT353

(Top View)

5

XX Y W X

2

1

XX: Identification code

Y: Year 0~9

 $\overline{\underline{W}}$: Week : A $^{\sim}$ Z : 1 $^{\sim}$ 26 week;

a~z: 27~52 week; z represents 52 and 53 week

X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G126W5	SOT25	PZ
74LVCE1G126SE	SOT353	PZ

(2) DFN1410

(Top View)

3

<u>XX</u> $\underline{Y}\underline{W}\underline{X}$ XX: Identification Code

Y: Year: 0~9

W: Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents

52 and 53 week

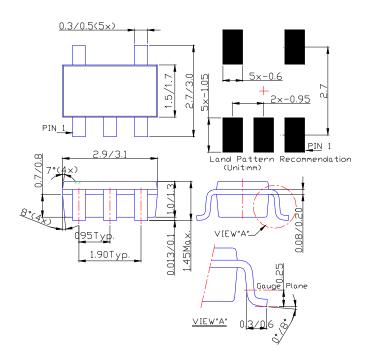
X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G126FZ4	DFN1410	PZ

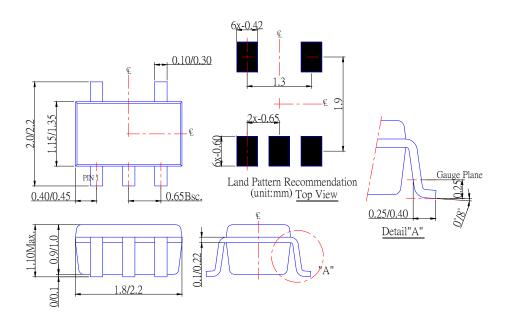


Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25



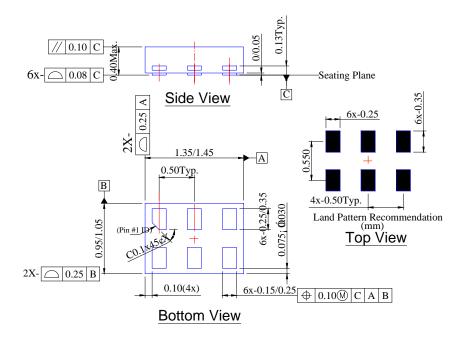
(2) Package Type: SOT353





Package Outline Dimensions (All Dimensions in mm)

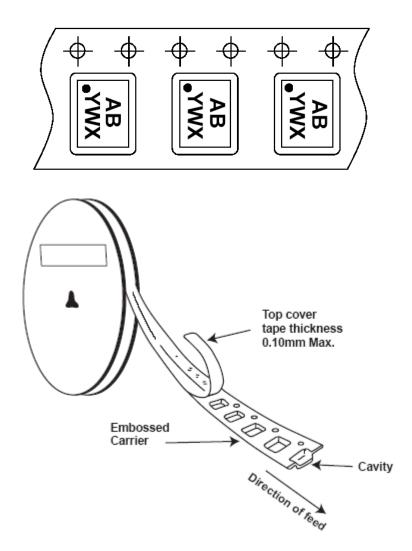
(3) Package Type: DFN1410





Taping Orientation (Note 7)

For DFN1410



Note: 7. The taping orientation of the other package type can be found on our website at http://www.diodes.com/datasheets/ap02007.pdf



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